

# TI Designs

## Using TI's TMS320C6657 Device to Implement Efficient OPUS Codec Solution



### Design Overview

This reference design provides an example of the ease of running the TI-optimized Opus encoder and decoder on the TMS320C6657 device. Because Opus supports a wide range of bit rates, frame sizes, and sampling rates, all with low delay, it has applicability for voice communications, networked audio, and even high-performance audio processing applications. This design also highlights the performance improvements achieved when implementing the Opus codec on a DSP, versus a general purpose processor like ARM. Depending upon the level of optimization of the code running on the general purpose processor, implementing the Opus Codec on a C66x TI DSP core can have 3x the performance of an ARM® Cortex®-A15 implementation.

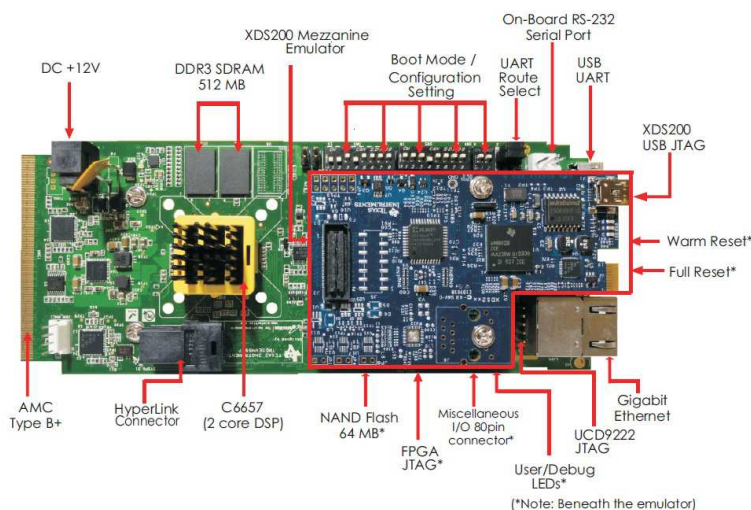
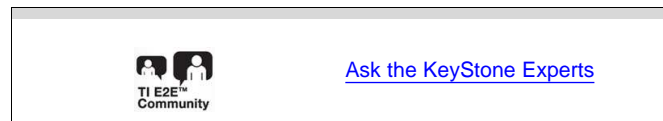
### Design Resources

- [TMS320C6657 EVM](#)
- [Speech Codes](#)
- [Opus codec page](#)
- [TMS320C6657 EVM](#)
- [BIOS MCSDK](#)
- [TIDEP0036](#)

- TMDS6657LS EVM Information
- Speech Codes for C66x-based Devices
- Download Opus Encoder and Decoder
- TMS320C6657 EVM Quick Setup Guide
- BIOS MCSDK User Guide
- TI Designs TIDEP0036

### Design Features

- This reference design is tested, and includes a hardware reference (EVM), software (Opus Codec package), and a user's guide.
- TMDSEVM6657 Lite EVM for a high performance, cost-efficient, standalone development platform, using the TMS320C6657 high-performance DSP based on TI's C66x Keystone multicore architecture. This design includes schematics, design files, and a bill of materials.
- TI-optimized Opus codec on the TI C66x DSP Core. The Opus codec package includes the codec, along with test application, user guides, and documentation.
- User's guide, including performance benchmarks versus the ARM Cortex A-15.



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# 1 Design Summary

Texas Instruments' C6000 Digital Signal Processors (DSPs) excel at implementing real-time audio codecs and enabling high-performance, cost-effective solutions for the voice infrastructure market. This design provides a reference for the Opus audio codec developed by the Internet Engineering Task Force (IETF), which provides unmatched performance across a wide band of bitrates. Opus is an open, royalty-free codec.

This design is implemented on the TMS320C6657 high-performance DSP based on TI's C66x Keystone multicore architecture. The C6657 Lite Evaluation Module (EVM) is a high performance, cost-efficient, standalone development platform that enables users to quickly evaluate and develop applications for the TMS320C6657 DSP. This design provides an example of the running TI's optimized Opus encoder and decoder on the TMS320C6657 processor.

## 1.1 Introduction to the TMS320C6657 and TMDSEVM6657LS EVM

The [TMS320C6657](#) is integrated with two C66x DSP cores running at 850 MHz, 1.0 GHz, or 1.25 GHz, supporting fixed and floating point operation. The TMS320C6657 can be used for a wide range of high-performance signal processing applications, such as speech and audio processing, avionics and defense, medical imaging, and building and factory automation. The C66x DSP is fully backward-compatible with all existing devices in the C6000 family of fixed and floating point DSPs.

The [TMDSEVM6657LS Lite EVM](#) is a single-width, double-height AMC form-factor card developed by eInfochips. The card enables developers to quickly start evaluating the TMS320C6657 processor and building applications around it. The EVM also serves as a hardware reference design platform for the TMS320C6657 DSP.

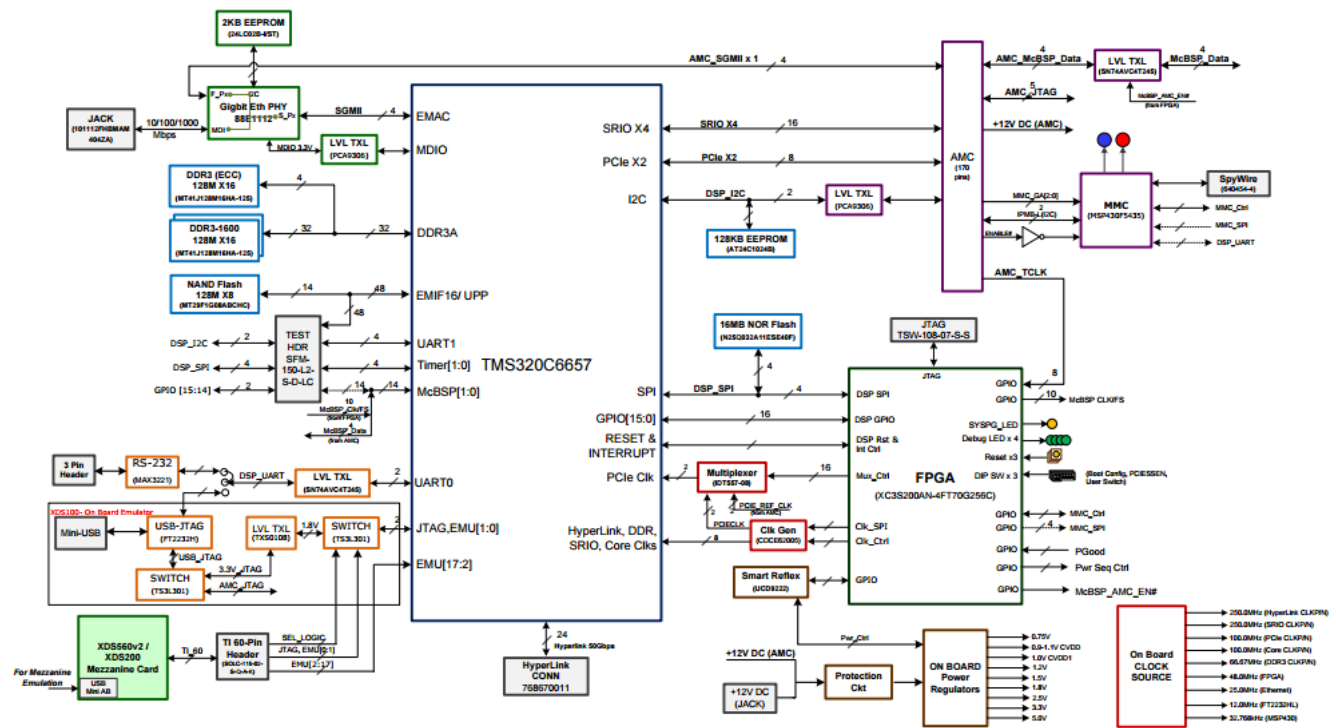


Figure 1. Block Diagram of TMDXEVM6657LE and TMDSEVM6657LS

## 1.2 Introduction to TI Opus C66x Codec

TI has implemented an Opus encoder and decoder on the C66x platform. This version of the codec has the following supported features:

- eXpressDSP Digital Media (XDM) interface complaint
- Optimized in Linear ASM, Scheduled ASM, and C implementation with Intrinsic
- Bit-exact with Opus open source standard version 1.1
- Based on Opus coding algorithm for speech and music signals sampled at either 48 KHz, 24 KHz, 16 KHz, 12 KHz, or 8 KHz
- Operates on variable frame sizes of 2.5 ms, 5 ms, 10 ms, 20 ms, 40 ms, and 60 ms
- Supports bit rates ranging from 6 kbps to 510 kbps
- Supports mono and stereo (2) channels at Encoder input and Decoder output
- Supports Forward Error Correction (FEC) at the Encoder
- Supports run-time data buffers relocation and table relocation
- Supports Big Endian and Little Endian modes of operation
- Supports COFF and ELF formats
- Run-time control of the complexity level, supported values from 0 to 10
- Run-time control of DTX
- Supports RTP payload format specified in by the reference C code (RFC 6716)
- Supports packet loss concealment as specified by the reference C code
- Validated on the TMS320C6678 device EVM using Code Composer Studio version 5.2 with the code generation tools version 7.3.2

The performance of a TI-optimized Opus codec (for the C66x DSP core) in Little Endian mode is shown in [Table 1](#). There is only a trivial difference between this and Big Endian mode.

**Table 1. Performance Statistics (in Megacycles/sec) on C66x**

Configuration	Performance Statistics (in Megacycles/sec) on C66x <sup>(1)</sup>									
	Average					Peak				
	NB	MB	WB	SWB	FB	NB	MB	WB	SWB	FB
Encoder – LE	8.15	10.45	12.72	9.71	15.56	9.81	12.46	14.5	10.63	22.42
Decoder – LE	1.38	1.75	2.32	7.56	16.83	1.7	2.79	2.82	8.91	17.78
Full Duplex – LE	9.53	12.2	15.04	17.27	32.39	11.51	15.25	17.32	19.54	40.2

<sup>(1)</sup> Measured with program and data memory, stack, and I/O buffers in internal Memory (L2 SRAM) and L1P and L1D caches are thrashed at frame boundaries. Average and peak MCPS measurements can vary by +/-5%. Measured with frame size = 20 ms, Complexity=3, VBR Enabled, FEC disabled.

The performance of a non-optimized Opus is tested on an ARM A15 with the same test vectors and configurations. The Opus 1.1 source code is obtained from <http://www.opus-codec.org/downloads/> and compiled into a Linux application (opus\_demo) running on the A15 core of TI's 66AK2H12. The A15 runs an Ubuntu 14.04 system with 1.0 GHz speed.

**Table 2. Performance Statistics (in Megacycles/sec) on ARM A15 Linux**

Configuration	Performance Statistics (in Megacycles/sec) on ARM A15 Linux									
	Average					Peak				
	NB	MB	WB	SWB	FB	NB	MB	WB	SWB	FB
Encoder – LE	16.94	23.28	31.27	15.86	26.48	29.1	30.85	45.6	30.8	42.25
Decoder – LE	2.42	3.31	4.68	10.38	16.55	7.95	11.75	12.8	23.3	30.55
Full Duplex – LE	19.36	26.59	35.95	26.24	43.03	37.05	42.6	58.4	54.1	72.8

Overall, the opus codec running on a TI C66x DSP core has 1.3x-3.4x the performance improvement over the A15 implementation.

## 2 Running Opus Codec on TMDSEVM6657LS Lite EVM

This section explains how to prepare the EVM and codec package, how to run the test example, and the expected result.

### 2.1 Prepare the EVM

1. First, unpack the EVM from the shipment box, and set the DSP bootmode to no-boot mode by following the pin setting at [http://processors.wiki.ti.com/index.php/TMDSEVM6657L\\_EVM\\_Hardware\\_Setup](http://processors.wiki.ti.com/index.php/TMDSEVM6657L_EVM_Hardware_Setup). Note that pin1 of SW3 defines the endianness of the system. Figure 2 illustrates the setting of no-boot mode with Little Endian, and the test example described in this design uses Little Endian. The customer may also switch the setting to Big Endian and use the Opus Big Endian package.

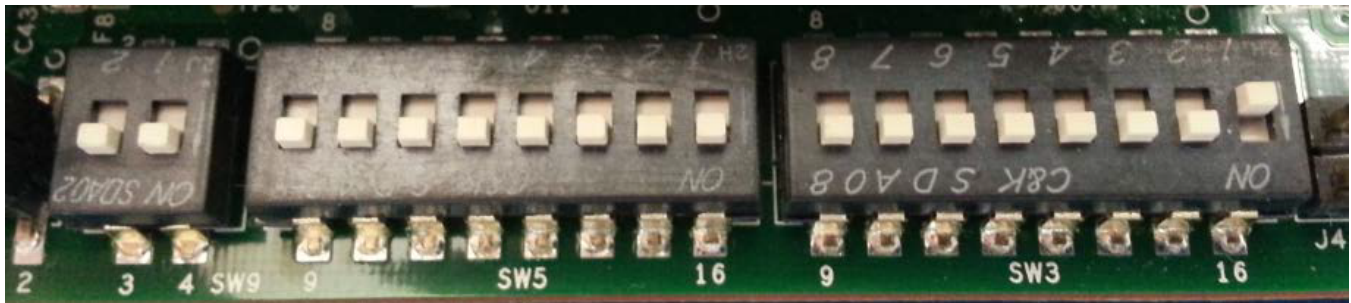


Figure 2. Switch Setting for No-Boot, Little Endian Mode

2. Create a CCXML configuration file for the CCS connection; CCS 5.2 or higher should support the TMS320C6657 device. If not, install the TI KeyStone1 Emupack from [http://software-dl.ti.com/sdoemb/sdoemb\\_public\\_sw/bios\\_mcsdk/latest/index\\_FDS.html](http://software-dl.ti.com/sdoemb/sdoemb_public_sw/bios_mcsdk/latest/index_FDS.html). Also add the GEL file to core 0 from <CCS\_INSTALLATION>\ccs\_base\emulation\boards\evmc6657\gel\evmc6657i.gel.

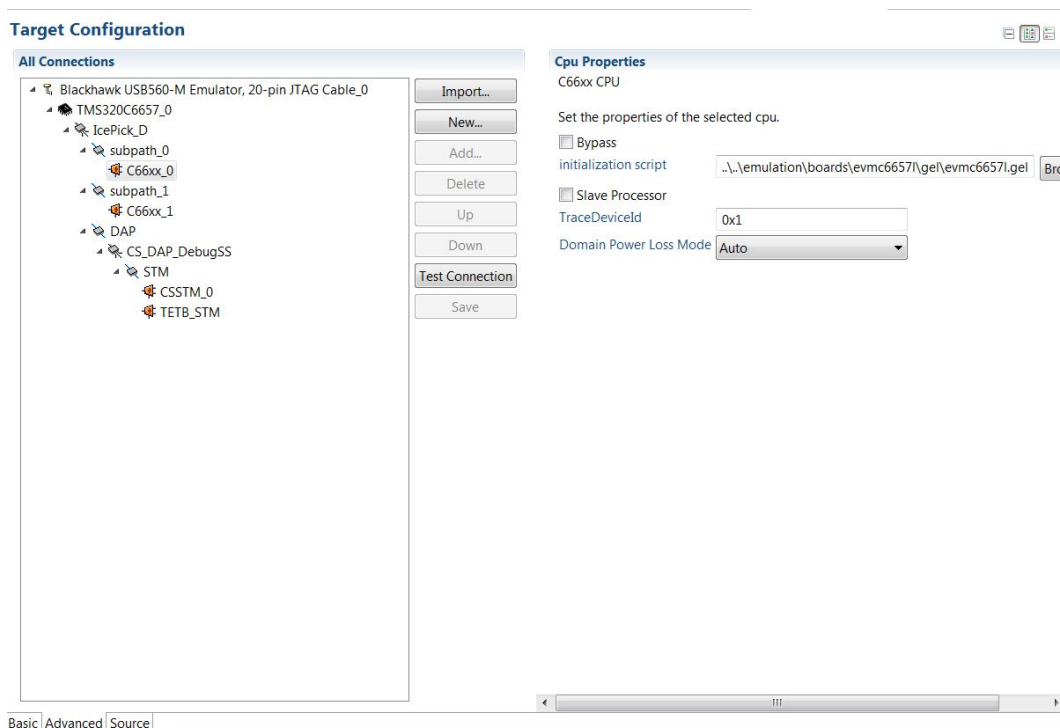


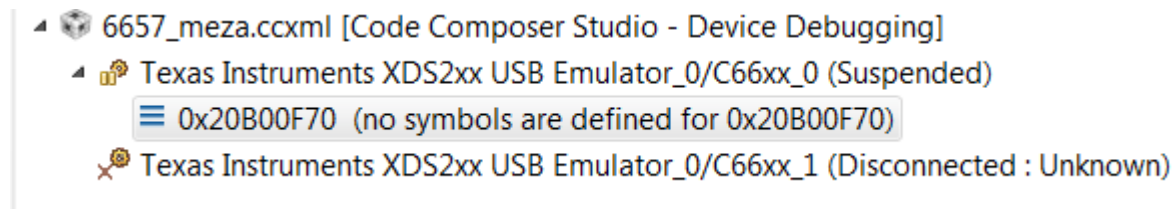
Figure 3. All Connections

3. Finally, launch the target and connect to core 0. You should see GEL runs and core 0 is halted:

```

C66xx_0: GEL Output: Setup_Memory_Map...
C66xx_0: GEL Output: Setup_Memory_Map... Done.
C66xx_0: GEL Output:
Connecting Target...
C66xx_0: GEL Output: DSP core #0
C66xx_0: GEL Output: C6657L GEL file Ver is 1.004
C66xx_0: GEL Output: Global Default Setup...
C66xx_0: GEL Output: Setup Cache...
C66xx_0: GEL Output: L1P = 32K
C66xx_0: GEL Output: L1D = 32K
C66xx_0: GEL Output: L2 = ALL SRAM
C66xx_0: GEL Output: Setup Cache... Done.
C66xx_0: GEL Output: Main PLL (PLL1) Setup ...
C66xx_0: GEL Output: PLL in Bypass ...
C66xx_0: GEL Output: PLL1 Setup for DSP @ 1000.0 MHz.
C66xx_0: GEL Output: SYSCLK2 = 333.3333 MHz, SYSCLK5 = 200.0 MHz.
C66xx_0: GEL Output: SYSCLK8 = 15.625 MHz.
C66xx_0: GEL Output: PLL1 Setup... Done.
C66xx_0: GEL Output: Power on all PSC modules and DSP domains...
C66xx_0: GEL Output: Power on all PSC modules and DSP domains... Done.
C66xx_0: GEL Output: DDR3 PLL (PLL2) Setup ...
C66xx_0: GEL Output: DDR3 PLL Setup... Done.
C66xx_0: GEL Output: DDR3 Init begin (1333 auto)
C66xx_0: GEL Output: XMC Setup ... Done
C66xx_0: GEL Output:
DDR3 initialization is complete.
C66xx_0: GEL Output: DDR3 Init done
C66xx_0: GEL Output: DDR3 memory test... Started
C66xx_0: GEL Output: DDR3 memory test... Passed
C66xx_0: GEL Output: PLL and DDR3 Initialization completed(0) ...
C66xx_0: GEL Output: configSGMIISerdes Setup... Begin
C66xx_0: GEL Output: SGMI SERDES has been configured.
C66xx_0: GEL Output: Enabling EDC ...
C66xx_0: GEL Output: L1P error detection logic is enabled.
C66xx_0: GEL Output: L2 error detection/correction logic is enabled.
C66xx_0: GEL Output: MSMC error detection/correction logic is enabled.
C66xx_0: GEL Output: Enabling EDC ...Done
C66xx_0: GEL Output: Global Default Setup... Done.

```



**Figure 4. Connect to core 0 of DSP**



## 2.2 Install Opus Codec Package and Dependencies

Download and install the latest Opus from [http://software-dl.ti.com/dsp/dsp\\_public\\_sw/codecs/C6X\\_Speech/2\\_00\\_000/index\\_FDS.html](http://software-dl.ti.com/dsp/dsp_public_sw/codecs/C6X_Speech/2_00_000/index_FDS.html).

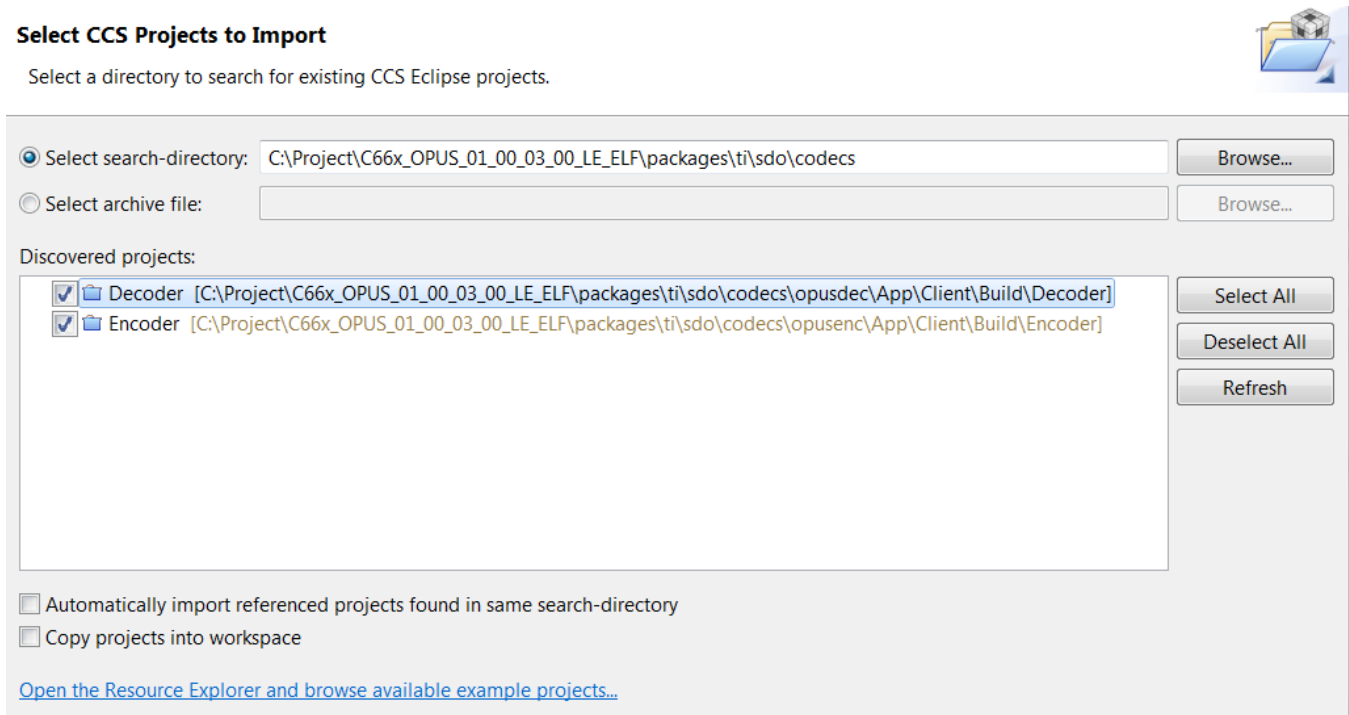
Check the user guide under <OPUS\_INSTALLATION>INSTALLATION>\packages\ti\sdo\codecs\opusenc\Docs to see what toolsets are used to build the test application. For example:

- Code Composer Studio version 5.2 with the code generation tools version 7.3.2.
- This version of the codec has been validated with
- SYS/BIOS version 6.33.04.39,
- XDC Tools version 3.23.02.47,
- XDAIS Tools version 7.22.00.03,
- Framework Component (FC) version 3.22.03.09

If you don't have all the toolsets, download and install them following the links in the user guide. Different versions of tools may work, but you may occasionally face tool compatibility issues.

## 2.3 Build the Test Applications

Import the existing CCS projects for the encoder and decoder:



**Figure 5. Import Opus Test Application CCS Projects**

Because the tools installation paths may differ from what were used when packaging the Opus codec, you may experience some CCS include path issues, as shown in [Figure 6](#), circled in the red box. Greyed-out paths must be resolved before building.

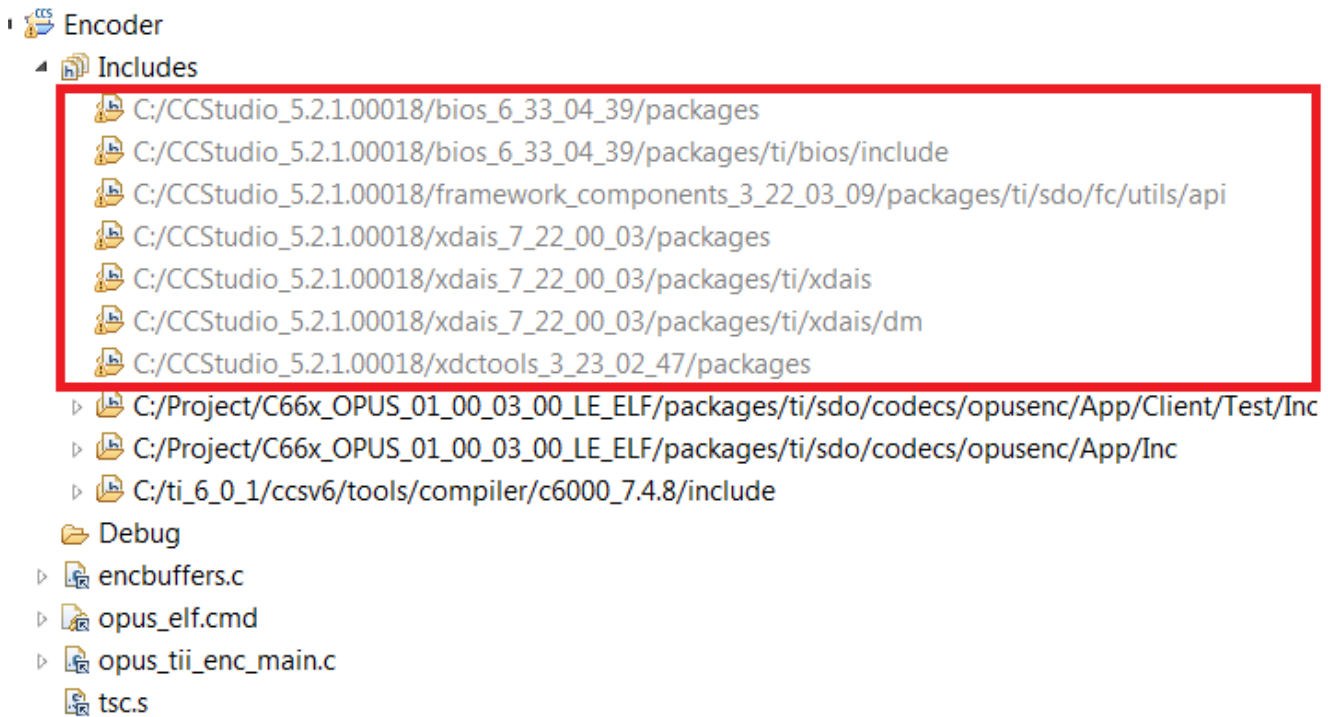


Figure 6. Check CCS Include Paths

This can be done by editing the Include Options in the project's Properties to match the installation and environment:

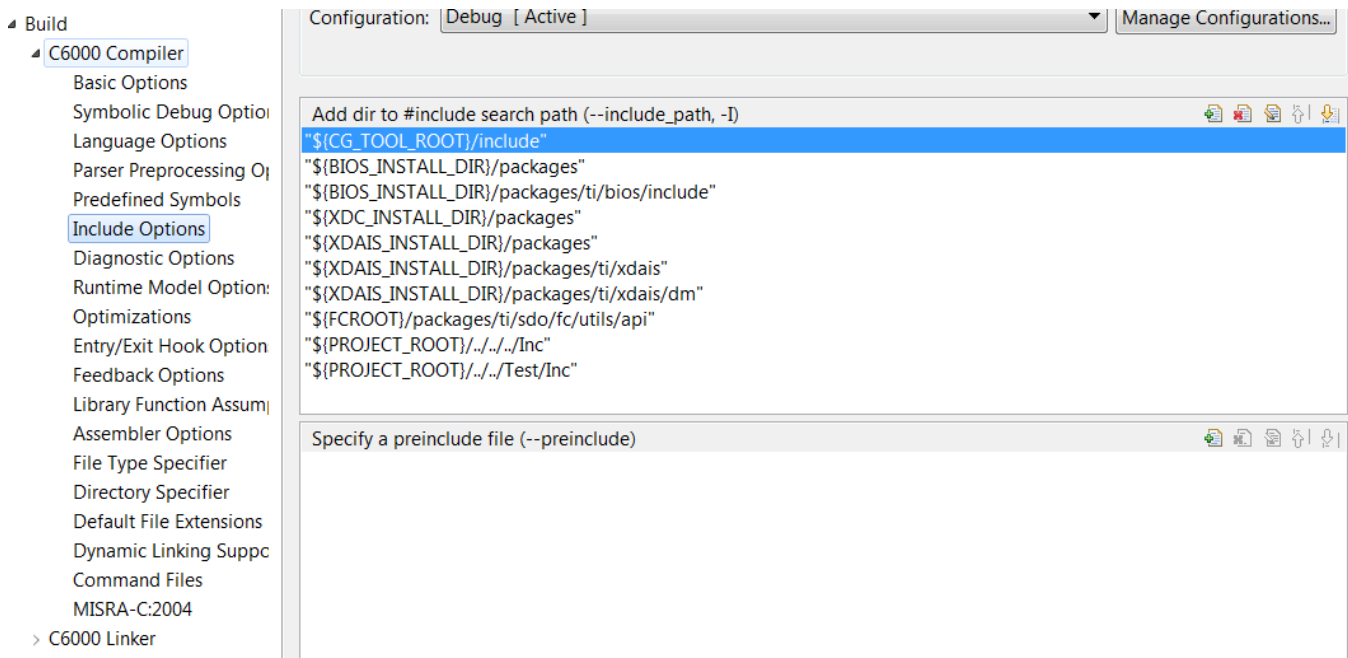


Figure 7. Resolve the Reference Paths to Installation and Environment

After resolving the correct paths, the project should be able to build. For an encoder project, Encoder.out and Encoder.map can be found in the packages\ti\sdo\codecs\opusenc\App\Client\Build\Encoder\Debug folder. For a decoder project, the same output can be found at the same location in the decoder folder.

## 2.4 Run the Test Applications

Load the DSP executable to core 0 and run.

The encoder takes a configuraion file stored at \App\Client\Test\Testvecs\ All\_test\_vectors\_enc.txt and runs. The configuration file specifies the test parameters, input vectors, and output reference vectors. You can edit this file for different test cases. The meaning of the configuration file is explained in the user guide. The output should appear like this:

```
[C66xx_0] Test Vector No. 1
Encoder Input : ..\..\..\test\testvecs\Input\sample.wav
Encoder Reference Output :
..\..\..\test\testvecs\Bitstream\sample_audio_48k_mono_128kbps_FB_c3.bit
Encoding 48000 Hz input at 128.000 kb/s in fullband mode with 480-sample frames.
Processing the frame: 1
Peak Cycles : 212971, at frame 1
Processing the frame: 2
Processing the frame: 3
Processing the frame: 4
Peak Cycles : 216889, at frame 4
Processing the frame: 5
Processing the frame: 6
Processing the frame: 7
...
Processing the frame: 457
Processing the frame: 458
Processing the frame: 459
Processing the frame: 460
COMPLETED TESTVECTOR, TOTAL FRAMES. 460
=====
END OF ALL TEST VECTORS
=====
```

If a mismatch between the encoder output and the reference is found, an error message is printed:

```
ENCODER TEST FAILED AT FRAME NO. ...
```

Similarly, you can load the decoder executable to core 0 and run. The decoder takes a configuration file stored at \App\Client\Test\Testvecs\All\_test\_vectors\_dec.txt. The output should look similar to that below, and any failures should be printed:

```
[C66xx_0] Decoding with 48000 Hz output (1 channels)
Processing the frame: 1
Peak Cycles : 176694, at frame 1
Processing the frame: 2
Processing the frame: 3
Processing the frame: 4
Peak Cycles : 181019, at frame 4
Processing the frame: 5
...
Processing the frame: 459
Processing the frame: 460
COMPLETED TESTVECTOR, TOTAL FRAMES. 460
=====
END OF ALL TEST VECTORS
=====
```

## 3 Acknowledgements and References

- *TMS320C6655/57 Fixed and Floating-Point Digital Signal Processor Data Manual* ([SPRS814A](http://www.ti.com/lit/zip/SPRS814A))
- *TMDXEVM6657L/LE/TMDSEVM6657LS Technical Reference Manual Version 2.1*, [https://www.einfochips.com/images/texas\\_instrument/TI-TMS320C6657-EVM/C6657%20Lite%20EVM\\_TechnicalReferenceManual.pdf](https://www.einfochips.com/images/texas_instrument/TI-TMS320C6657-EVM/C6657%20Lite%20EVM_TechnicalReferenceManual.pdf)
- *OPUS Encoder/Decoder (v01.00.03) on C66x Data Sheet*



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